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Changzhou Mingseal Robot Technology Co., Ltd.
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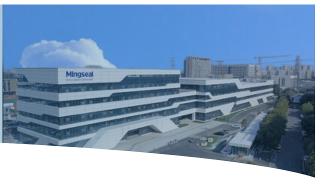

AC100 Series High Speed Die Bonder Mobile Communication QFN MEMS SIP OTHER Automotive industry Aiot Filp Chip Inspection

Our Product Introduction

Basic Information

Place of Origin:	China
Brand Name:	MingSeal
Certification:	ISO
Model Number:	AC100
Minimum Order Quantity:	1
Price:	$1000-$150000
Packaging Details:	WOODEN
Delivery Time:	5-60 days
Payment Terms:	L/C, T/T, D/A, D/P, MoneyGram, Western Union

Product Specification

Automatic Grade:	Automatic
Condition:	New
After-sales Service Provided:	Engineers Available To Service Machinery Overseas,Video Technical Support,Online Support,Field Installation,commissioning And Training
Dimension(l*w*h):	1180 X 1310 X 1700mm
Product Name:	AS200 Series High Speed Die Bonder
Weight:	Around 1400kg
Voltage:	220 VAC(@ 50/60Hz)
Highlight:	**SMD LED pick and place solder paste dispenser , LGA pick and place solder paste dispenser , LGA smd led pick and place machine**

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AS200 Series High Speed Die Bonder

The AS200 series high- speed dispensing and bonding machine can be applied in the advanced MEMS bonding process to achieve die bonding of high-density and high-reliability, and supports versatile packages, such as QFN, SIP, LGA , BGA and FC , for a variety of different application
scenarios . Various advanced technologies and innovative processes are used in the design and production of the AS200 to ensure its high speed, high accuracy and versatility.
The AS200's modular whole-set design allows for rapid inline production and supports " Direct Attach-Flip Chip" function switching, making production more flexible and efficient.
In addition, the AS200 can be optionally designed to meet the DAF film heating process through its forward-looking track design , and achieve stable , high-speed and high-precision production through the optimized design of the dispensing and pick & place mechanisms and the reconfiguration of the motion logic.
The technical specifications and performance of AS200 meet international standards , making it a high performance , highly reliable and internationally competitive dispensing and die attaching machine, enabling customers to have minimal cost and maximum ROI.

Features and Advantages

High-speed / high-precision die bonding process
Nearest handling path planning as per enabled modules.
Automatic calibration and bonding force monitoring with editable cycles.
Active vibration suppression system with <5um amplitude in the die bonding area at full speed.
Lightweight and rigid high-speed die bonding module with a max. speed of 15m/s.
Expandability and configurability
Dust-proof jacket selectable.
Loading methods compatible for multiple forms of substrate/frame.
Substrate heating by changing tooling supportive.
Thin chip picking process by changing configuration supportive.
Capable of switchingand between Face-up bonding and Flip-chip bonding by adding and replacing configurations.

Stable glue control process
Visual inspection automatic adjustment of glue volume.
Optimal high speed and low vibration glue dispensing path planning.
Self-developed high precision dispensing controller of international standard.
Innovative lightweight decoupling dispensing mechanism with a max. accelerated velocity of 2.5g.

Advanced technology and innovative process
Core functions and technical parameters are on par with international competitors.
Core modules are self-developed to ensure subsequent expansion and upgrading.
Module-based agile architecture design to build advanced software matrix capability.
Capable of handling 12-inch wafers, comparable to competing 8-inch die bonder in terms of footprint.

AC200 Application Fields

Sensor Housing Mounting
Holder Mounting
Reinforcement Plate Mountin
Main Camera And Auxiliary Camera Mounting
VCM Mounting

Technical Specifications

Model AS200		
Machine Size	Footprint (WxDxH)	1180 X 1310 X 1700mm
	Weight	around 1400kg
Facilities	Voltage	220 VAC(@ 50/60Hz)
	Rated power	1300VA
	Compressed air	Min. 0.5MPa
	Vacuum level	Min. -0.08MPa
	Nitrogen	0.2 - 0.6MPa
Wafer and Chip Size	Wafer size	6" - 12"
	Wafer table size	8" - 12"
	Chip size	0.25 - 15mm
	Process types	Epoxy DA/FC/DAF
Substrate/Lead frame Size	Width	20 - 110mm
	Length	110 - 310mm
	Thickness	0.1 - 2.5mm
Process	Bond force	0.3 - 20N
	Wafer table rotation	0 - 360°
	Min. cycle time	180ms
Accuracy/Productivity	Standard accuracy mode	±20um/0.5 ° (3σ)
	High accuracy mode	±12.5um/0.5 ° (3σ)
	Uptime	>98%

	Mean time without failure	>168 hours

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